

IN THE CLAIMS:

1. (Currently Amended) A positive photosensitive composition comprising:

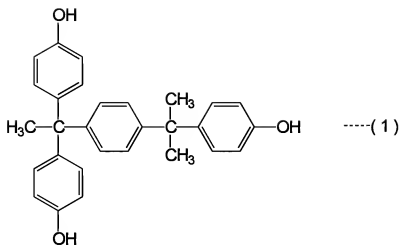
(A) an alkali soluble organic high molecular substance having a phenolic hydroxyl group,

(B) a photo-thermal conversion material that absorbs infrared rays from an image exposure light source and converts it to heat,

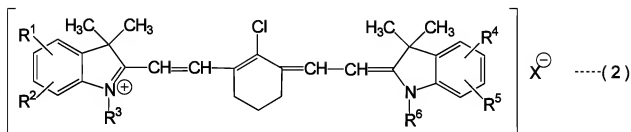
(C) at least one resin selected from the group consisting of: (1) vinylpyrrolidone/vinyl acetate copolymer, (2) vinylpyrrolidone/dimethylaminoethyl methacrylate copolymer, (3) vinylpyrrolidone/vinyl caprolactam/ dimethylaminoethyl methacrylate copolymer, (4) polyvinyl acetate, (5) polyvinyl butyral, (6) polyvinyl formal, (7) styrene/maleic acid copolymer, (8) terpene phenol resin, (9) alkylphenol resin, (10) melamine/formaldehyde resin, and (11) ketone resin, and

(D) a dissolution inhibitor.

2. (Original) The positive photosensitive composition according to claim 1, wherein the dissolution inhibitor (D) is a compound represented by the following chemical formula (1).



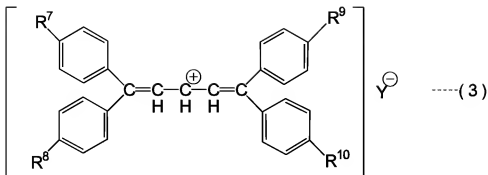
____ 3. (Currently Amended) The positive photosensitive composition according to claim 1 or 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (2).



wherein each of “R¹” to “R⁶” independently represents a hydrogen atom, an alkyl group having 1 to 3 carbon atoms, or an alkoxy group having 1 to 3 carbon atoms, and “X” represents a halogen atom, ClO₄, BF₄, p-CH₃C₆H₄SO₃, or PF₆.

____ 4. (Currently Amended) The positive photosensitive composition according to claim 1 or 2, wherein the photo-thermal conversion material (B) is a compound represented by the

following formula (3).



wherein each of “R⁷”~“R¹⁰” independently represents a hydrogen atom, a methoxyl group, N(CH₃)₂, or N(C₂H₅)₂, and “Y” represents C₄H₉-B(C₆H₅)₃, p-CH₃C₆H₄SO₃, or CF₃SO₃.

5. (Currently Amended) A photofabrication method comprising:

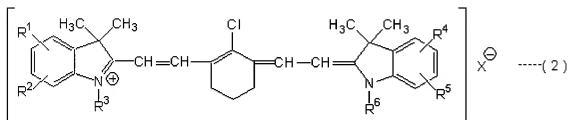
exposing using the positive photosensitive composition according to any of claims 1 to 4 as defined in claim 1 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image.

6. (Original) The photo fabrication method according to claim 5, which is applied to production of a printing plate, an electronic component and a precision equipment component.

7. (Currently Amended) A plate-making method comprising:

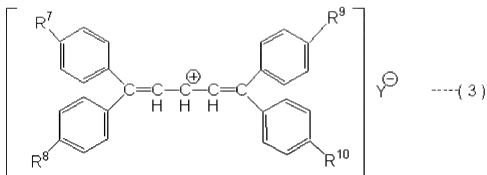
exposing using the positive photosensitive composition according to any of claims 1 to 4 as defined in claim 1 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image.

____ 8. (New) The positive photosensitive composition according to claim 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (2).



wherein each of "R¹" to "R⁶" independently represents a hydrogen atom, an alkyl group having 1 to 3 carbon atoms, or an alkoxy group having 1 to 3 carbon atoms, and "X" represents a halogen atom, ClO₄, BF₄, p-CH₃C₆H₄SO₃, or PF₆._____

____ 9. (New) The positive photosensitive composition according to claim 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (3).



wherein each of “R⁷”~“R¹⁰” independently represents a hydrogen atom, a methoxyl group, N(CH₃)₂, or N(C₂H₅)₂, and “Y” represents C₄H₉-B(C₆H₅)₃, p-CH₃C₆H₄SO₃, or CF₃SO₃.

10. (New) A photofabrication method comprising:

exposing the positive photosensitive composition as defined in claim 2 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image.

11. (New) The photofabrication method according to claim 10, which is applied to production of a printing plate, an electronic component and a precision equipment component.

12. (New) A plate-making method comprising:

exposing the positive photosensitive composition as defined in claim 2 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image.